

CROWELL & MORING, LLP Intellectual Property Group P.O. Box 14300 Washington, D.C. 20044-4300 202) 624-2500

October 3, 2003

Customer No.

23911

Re: New U.S. Patent Appln.

Our Ref: 010986.52822US

Mail Stop PATENT APPLICATION

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing is the patent application of:

Hiroshi SHINRIKI and Shintaro AOYAMA

entitled: Method of and Apparatus for Processing Substrates

Enclosed are:

- 1. Specification, including <u>14</u> claims (pages <u>16</u>), in Japanese.
- 2. 8 Sheets of drawings showing Figs. 1-8.
- 3. Application Data Sheet
- 4. Priority is being claimed under 35 U.S.C. §119 and 37 C.F.R. §1.55 based on Priority Document 2002-291579, filed in Japan on October 3, 2002.

The filing fee is being deferred.

Respectfully submitted,

Herbert I. Cantor

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HIC:tcv

